

4

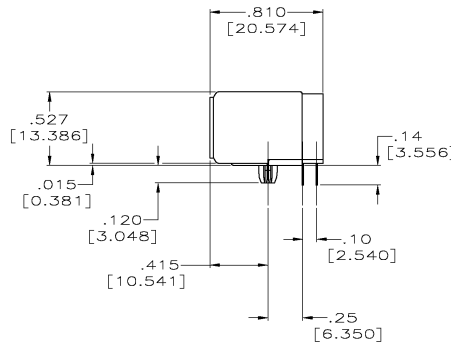
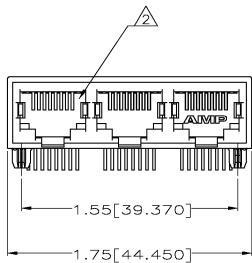
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LOC	DISB	REVISIONS					
		P	LTR	DESCRIPTION	DATE	OWN	APPD
AA	22	A		ECCS11-0201-04	10MAY2005	LAM	SF

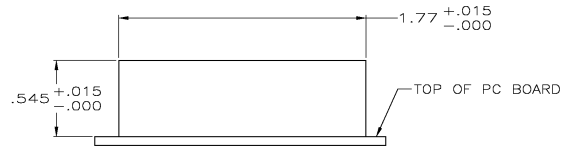
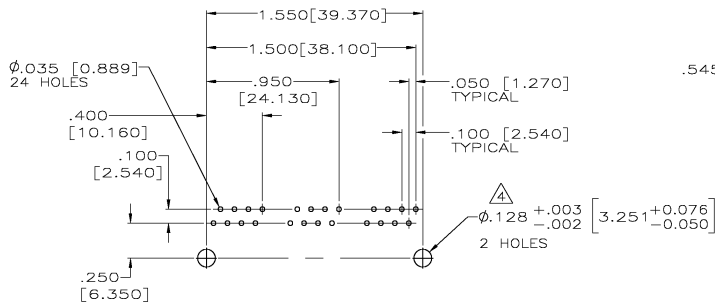


- MATERIAL: HOUSING - HTN NYLON, BLACK, IR REFLOW PROCESSING COMPATIBLE, UL 94V-0. TERMINALS - .013[0.33] THICK PHOS BRONZE PLATED WITH .000050[1.27µm] THICK HARD GOLD IN LOCALIZED AREA AND .000150[3.81µm] THICK MATTE TIN IN SOLDER AREA OVER .000050[1.27 µm] THICK NICKEL UNDERPLATE.

△ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

3. ALL DIMENSIONS SHOWN IN BRACKETS [] ARE IN MILLIMETERS.

△ USE #30 DRILL BIT OR 3.25 MM DRILL BIT WHEN PRODUCING THESE PRINTED CIRCUIT BOARD HOLES.



SUGGESTED PANEL CUTOUT

SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SEE APPLICATION SPECIFICATION

5557561-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: V. SLACK / A. MAYER	DATE: 10MAY2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: INCHES		CHK: J. WESTMAN	DATE: 10MAY2005	NAME: S. ELCKINGER	
TOLERANCE LIMITS: DIMENSIONS UNLESS NOTED		PRODUCT SPEC: 108-1163		MODULAR JACK ASSEMBLY, THREE PORT, 8 POSITION, RIGHT ANGLE	
0 P.L.C. ± .010		APPLICATION SPEC: 114-2048		SIZE: CASE CODE: DRAWING NO: A2 00779 C=5557561	
1 P.L.C. ± .005		HEIGHT: -		RESTRICTED TO: -	
2 P.L.C. ± .0025		CUSTOMER DRAWING		SCALE: 2:1 SHEET 1 OF 1 REV A	
3 P.L.C. ± .0015					
4 P.L.C. ± .0010					
ANGLES: ± .5°					
FINISH: SEE NOTE 1		SEE NOTE 1			